

Jowat-Toptherm[®] 221.00 & 221.80









Unfilled PO hot melt adhesives for profile wrapping

- Wide range of applications with different materials
- High heat resistance
- Very high initial strength



Two Powerful Adhesives That Will Not Let You Down

Does your manufacturing process involve the wrapping of demanding profiles for even more demanding customers? **Jowat-Toptherm® 221.00** and **Jowat-Toptherm® 221.80** are two adhesives characterized by a wide range of adhesion and high initial strength that have been tried and trusted by many processors. The granulate is easy to dispense and melt according to your needs, for example in an extruder or a melting tank, and can then be applied directly via roller or slot nozzle.

Jowat-Toptherm® 221.80 impresses in wrapping applications with solid wood, particleboard or fiberboard in combination with thermoplastic foils, CPL and fleece-backed thin veneer at low to medium feed speeds.

Jowat-Toptherm® 221.00 facilitates the reliable bonding of thick foils and veneer with high restoring forces at even high feed speeds—the problem-solver for demanding applications.

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Unfilled PO hot melt adhesives for profile wrapping

Jowat-Toptherm®		221.00	221.80
Based on		PO	РО
Viscosity	at 200°C	~23,200 mPas	~11,550 mPas
Processing temperature		180°C–200°C	180°C-200°C
Open time	at 190°C	~8 s	~15 s
Initial strength		000	
Range of adhesion		000	000
Feed speed			
Heat resistance			000

The information given in this leaflet is based on test results from our laboratories as well as on experience gained in the field, and does in no way constitute any guarantee of properties. Due to the wide range of different applications, substrates, and processing methods beyond our control, no liability may be derived from these indications nor from the information provided by our free technical advisory service. Before processing, please request the corresponding data sheet and observe the information in it! Customer trials under everyday conditions, testing for suitability at normal processing conditions, and appropriate fit-for-purpose testing are absolutely necessary. For the specifications as well as further information, please refer to the latest technical data sheets.

